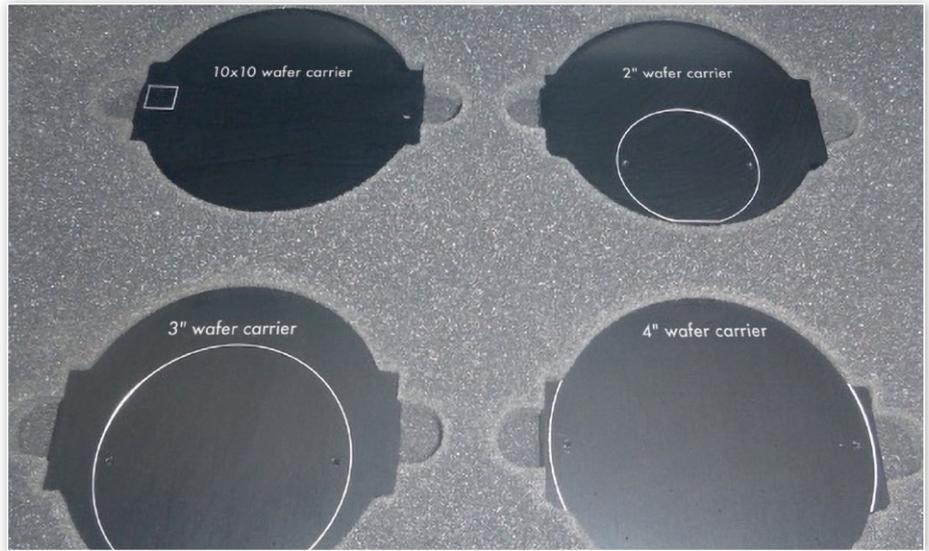
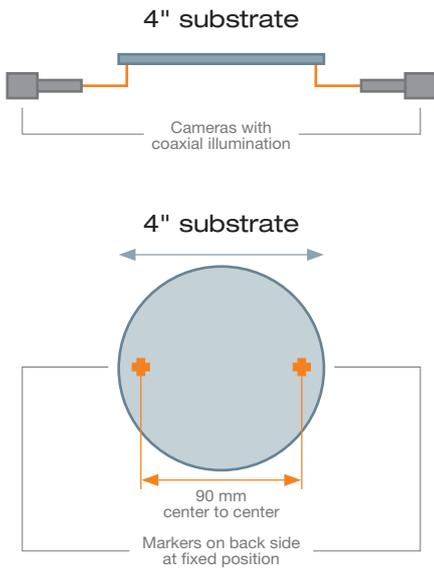


# Back Side Alignment



Concept of back side alignment and images of the corresponding wafer carriers with marker windows

## Description

Back Side Alignment (BSA) on the PICOMASTER systems is performed by means of 2 cameras with telecentric illumination and vision software for processing the images. The cameras are mounted on two fixed positions and are only able to capture images from the back side at those positions. Vision software processes the images and enables the system to automatically detect shapes and measure their position.

## Specifications and performance

Camera	5.2M pixel monochrome, USB 3 interface
Field of view	2500 x 2000 $\mu\text{m}$
Pixel resolution	1 $\mu\text{m}$
Illumination	568 nm wavelength coaxial telecentric
Software	Cognex VPRO or Adaptive Vision Studio
Measurement accuracy (by interpolating)	< 100 nm
Alignment accuracy	< 2 $\mu\text{m}$
Default marker window positions	45 mm from the center on the left and right side

### Get in touch

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